- **Members of the Texas Instruments Widebus™ Family**

- **State-of-the-Art EPIC-IIB™ BiCMOS Design Significantly Reduces Power Dissipation**

- **Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C**

- **Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise**

- **Flow-Through Architecture Optimizes PCB Layout**

- **High-Drive Outputs (–32-mA I_{OH}, 64-mA I_{OL})**

- **Latch-Up Performance Exceeds 500 mA Per JESD 17**

- **ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)**

- **Package Options Include Plastic 300-mil Shrink Small-Outline (DL), Thin Shrink Small-Outline (DGG), and Thin Very Small-Outline (DGV) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings**

SN54ABT16241A . . . WD PACKAGE
SN74ABT16241A . . . DGG, DGV, OR DL PACKAGE
(TOP VIEW)

1OE	1	48	2OE
1Y1	2	47	1A1
1Y2	3	46	1A2
GND	4	45	GND
1Y3	5	44	1A3
1Y4	6	43	1A4
V_{CC}	7	42	V_{CC}
2Y1	8	41	2A1
2Y2	9	40	2A2
GND	10	39	GND
2Y3	11	38	2A3
2Y4	12	37	2A4
3Y1	13	36	3A1
3Y2	14	35	3A2
GND	15	34	GND
3Y3	16	33	3A3
3Y4	17	32	3A4
V_{CC}	18	31	V_{CC}
4Y1	19	30	4A1
4Y2	20	29	4A2
GND	21	28	GND
4Y3	22	27	4A3
4Y4	23	26	4A4
4OE	24	25	3OE
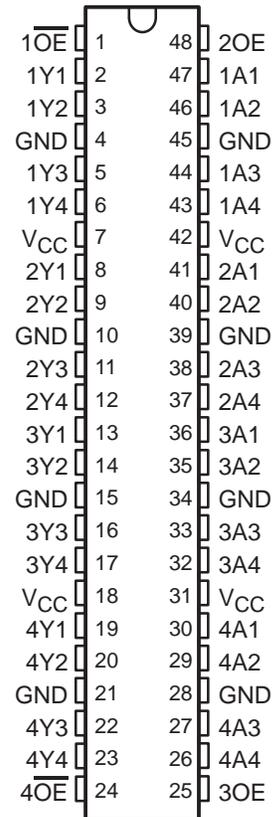
description

The 'ABT16241A devices are 16-bit buffers and line drivers designed specifically to improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters.

These devices can be used as four 4-bit buffers, two 8-bit buffers, or one 16-bit buffer. These devices provide true outputs and complementary output-enable (OE and $\overline{OE}$) inputs.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver. OE should be tied to GND through a pulldown resistor; the minimum value of the resistor is determined by the current-sourcing capability of the driver.

The SN54ABT16241A is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT16241A is characterized for operation from –40°C to 85°C.

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TEXAS INSTRUMENTS

SN54ABT16241A, SN74ABT16241A
16-BIT BUFFERS/DRIVERS
WITH 3-STATE OUTPUTS

FUNCTION TABLES

INPUTS		OUTPUTS
1$\overline{\text{OE}}$, 4$\overline{\text{OE}}$	1A, 4A	1Y, 4Y
L	H	H
L	L	L
H	X	Z

INPUTS		OUTPUTS
2OE, 3OE	2A, 3A	2Y, 3Y
H	H	H
H	L	L
L	X	Z

logic symbol†
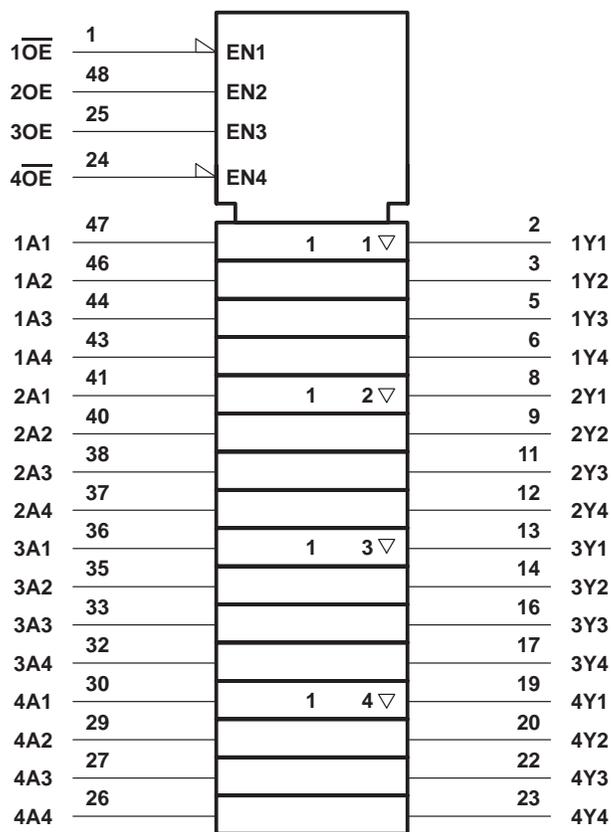
† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

TEXAS INSTRUMENTS

POST OFFICE BOX 655303 ● DALLAS, TEXAS 75265

logic diagram (positive logic)

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} .... –0.5 V to 7 V
Input voltage range, V_I (see Note 1) .... –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O .... –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABT16241A .... 96 mA
SN74ABT16241A .... 128 mA
Input clamp current, I_{IK} ($V_I < 0$) .... –18 mA
Output clamp current, I_{OK} ($V_O < 0$) .... –50 mA
Package thermal impedance, θ_{JA} (see Note 2): DGG package .... 89°C/W
DGV package .... 93°C/W
DL package .... 94°C/W
Storage temperature range, T_{stg} .... –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 3)

			SN54ABT16241A		SN74ABT16241A		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current			−24		−32	mA
I_{OL}	Low-level output current			48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
T_A	Operating free-air temperature		−55	125	−40	85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		$T_A = 25°C$			SN54ABT16241A		SN74ABT16241A		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = −18 mA			−1.2		−1.2		−1.2	V
V_{OH}		V_{CC} = 4.5 V,	I_{OH} = −3 mA	2.5			2.5		2.5		V
		V_{CC} = 5 V,	I_{OH} = −3 mA	3			3		3		
		V_{CC} = 4.5 V	I_{OH} = −24 mA	2			2				
			I_{OH} = −32 mA	2*					2		
V_{OL}		V_{CC} = 4.5 V	I_{OL} = 48 mA			0.55		0.55			V
			I_{OL} = 64 mA			0.55*				0.55	
V_{hys}					100						mV
I_I		V_{CC} = 5.5 V,	$V_I = V_{CC}$ or GND			±1		±1		±1	µA
I_{OZH}		V_{CC} = 5.5 V,	V_O = 2.7 V			10		10		10	µA
I_{OZL}		V_{CC} = 5.5 V,	V_O = 0.5 V			−10		−10		−10	µA
I_{off}		V_{CC} = 0,	V_I or $V_O \leq$ 4.5 V			±100				±100	µA
I_{CEX}		V_{CC} = 5.5 V, V_O = 5.5 V	Outputs high			50		50		50	µA
$I_O‡$		V_{CC} = 5.5 V,	V_O = 2.5 V	−50	−100	−180	−50	−180	−50	−180	mA
I_{CC}		V_{CC} = 5.5 V, I_O = 0, $V_I = V_{CC}$ or GND	Outputs high			3		3		3	mA
			Outputs low			34		34		34	
			Outputs disabled			3		3		3	
$\Delta I_{CC}§$	Data inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND	Outputs enabled			1		1.5		1	mA
			Outputs disabled			0.05		1		0.05	
	Control inputs	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				1.5		1.5		1.5	
C_i		V_I = 2.5 V or 0.5 V			3.5						pF
C_o		V_O = 2.5 V or 0.5 V			7.5						pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.
† All typical values are at V_{CC} = 5 V.
‡ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
§ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

TEXAS INSTRUMENTS

POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54ABT16241A					UNIT
			V_{CC} = 5 V, T_A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
t_{PLH}	A	Y	0.9	2.7	3.4	0.9	3.8	ns
t_{PHL}			0.9	2.7	3.9	0.9	4.6	
t_{PZH}	OE or $\overline{OE}$	Y	1.2	3.3	4.2	1.2	5.1	ns
t_{PZL}			1.3	3.4	5.9	1.3	7	
t_{PHZ}	OE or $\overline{OE}$	Y	1.5	4.1	5.5	1.5	7	ns
t_{PLZ}			1.7	3.6	5.1	1.7	5.7	

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN74ABT16241A					UNIT
			V_{CC} = 5 V, T_A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
t_{PLH}	A	Y	1	2.7	3.4	1	3.7	ns
t_{PHL}			1	2.7	3.9	1	4.5	
t_{PZH}	OE or $\overline{OE}$	Y	1.2	3.3	4.2	1.2	5	ns
t_{PZL}			1.3	3.4	5.9	1.3	6.9	
t_{PHZ}	OE or $\overline{OE}$	Y	1.5	4.1	5.2	1.5	6.2	ns
t_{PLZ}			1.7	3.6	5.1	1.7	5.6	

TEXAS
INSTRUMENTS

PARAMETER MEASUREMENT INFORMATION
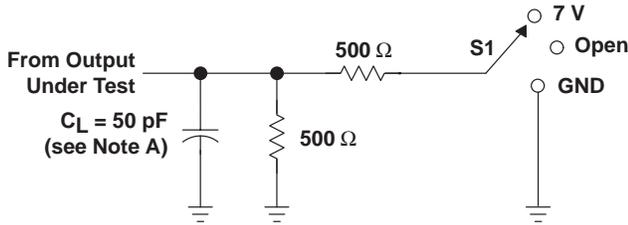
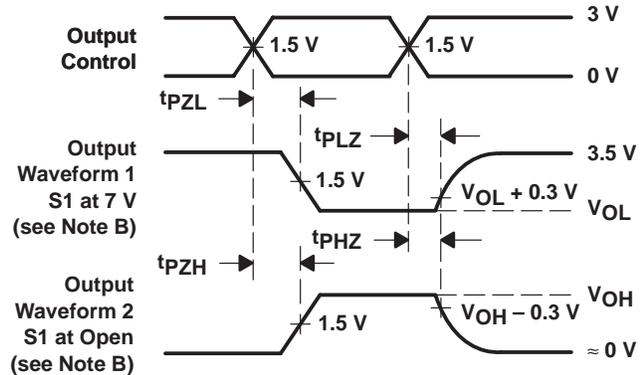| TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open

LOAD CIRCUIT
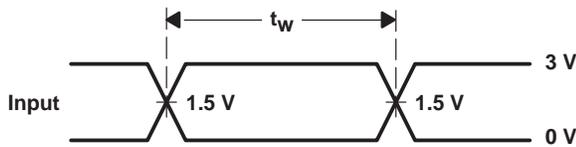
VOLTAGE WAVEFORMS
PULSE DURATION
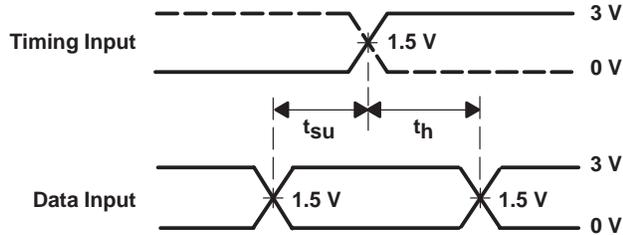
VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES
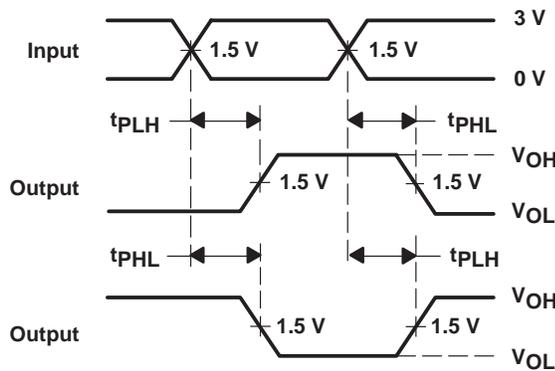
VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS

VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
   B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control.
      Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
   C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
   D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

TEXAS
INSTRUMENTS
POST OFFICE BOX 655303 ● DALLAS, TEXAS 75265

PACKAGE OPTION ADDENDUM

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
SN74ABT16241ADGGR	Active	Production	TSSOP (DGG) | 48	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT16241A
SN74ABT16241ADGGR.B	Active	Production	TSSOP (DGG) | 48	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT16241A
SN74ABT16241ADGVR	Active	Production	TVSOP (DGV) | 48	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AH241A
SN74ABT16241ADGVR.B	Active	Production	TVSOP (DGV) | 48	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AH241A
SN74ABT16241ADL	Active	Production	SSOP (DL) | 48	25 | TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT16241A
SN74ABT16241ADL.B	Active	Production	SSOP (DL) | 48	25 | TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT16241A
SN74ABT16241ADLR	Active	Production	SSOP (DL) | 48	1000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT16241A
SN74ABT16241ADLR.B	Active	Production	SSOP (DL) | 48	1000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT16241A
SN74ABT16241ADLRG4	Active	Production	SSOP (DL) | 48	1000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT16241A

(1) Status: For more details on status, see our product life cycle.

(2) Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.
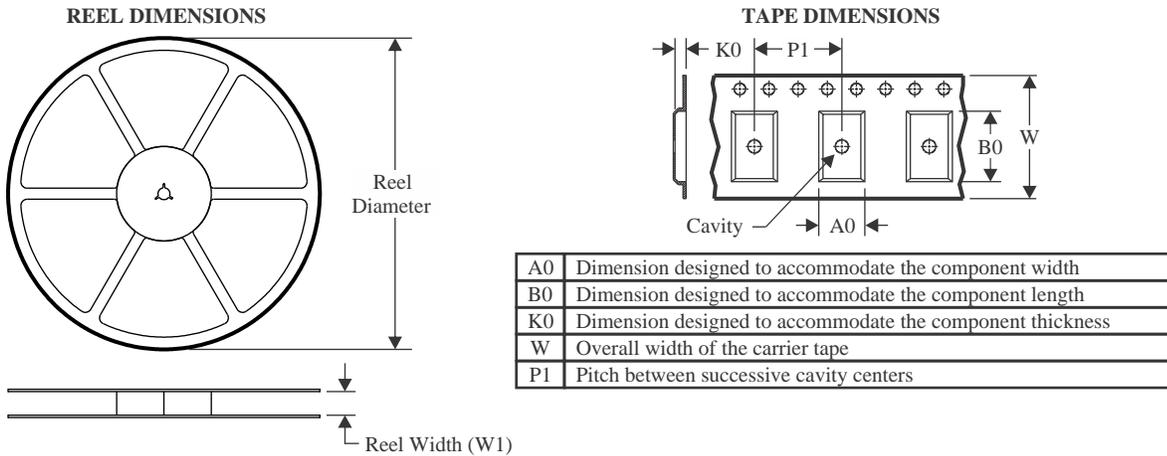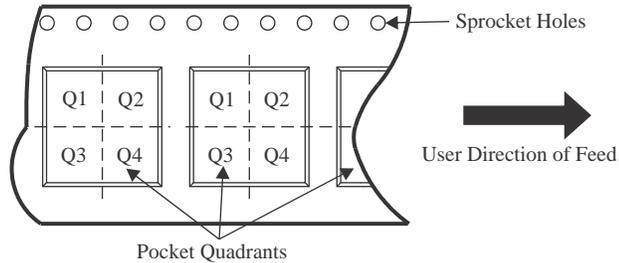
(6) Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION

REEL DIMENSIONS

TAPE DIMENSIONS

A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ABT16241ADGGR	TSSOP	DGG	48	2000	330.0	24.4	8.6	13.0	1.8	12.0	24.0	Q1
SN74ABT16241ADGVR	TVSOP	DGV	48	2000	330.0	16.4	7.1	10.2	1.6	12.0	16.0	Q1
SN74ABT16241ADLR	SSOP	DL	48	1000	330.0	32.4	11.35	16.2	3.1	16.0	32.0	Q1

TAPE AND REEL BOX DIMENSIONS
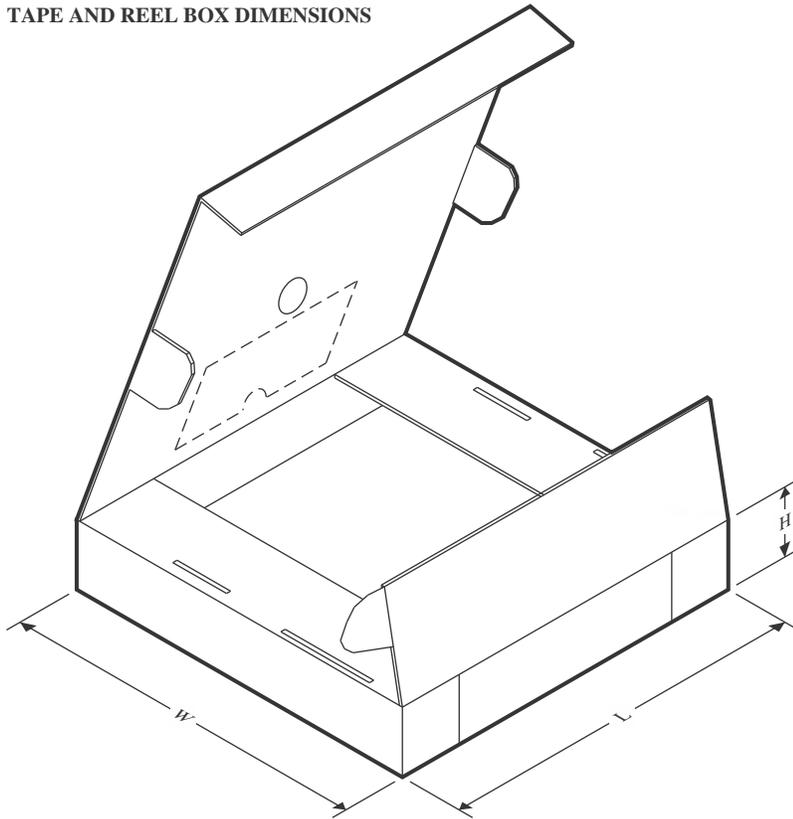
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ABT16241ADGGR	TSSOP	DGG	48	2000	356.0	356.0	45.0
SN74ABT16241ADGVR	TVSOP	DGV	48	2000	353.0	353.0	32.0
SN74ABT16241ADLR	SSOP	DL	48	1000	356.0	356.0	53.0

TUBE

T - Tube height

L - Tube length

W - Tube width

B - Alignment groove width

*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN74ABT16241ADL	DL	SSOP	48	25	473.7	14.24	5110	7.87
SN74ABT16241ADL.B	DL	SSOP	48	25	473.7	14.24	5110	7.87

DGV (R-PDSO-G**)   **PLASTIC SMALL-OUTLINE**

24 PINS SHOWN
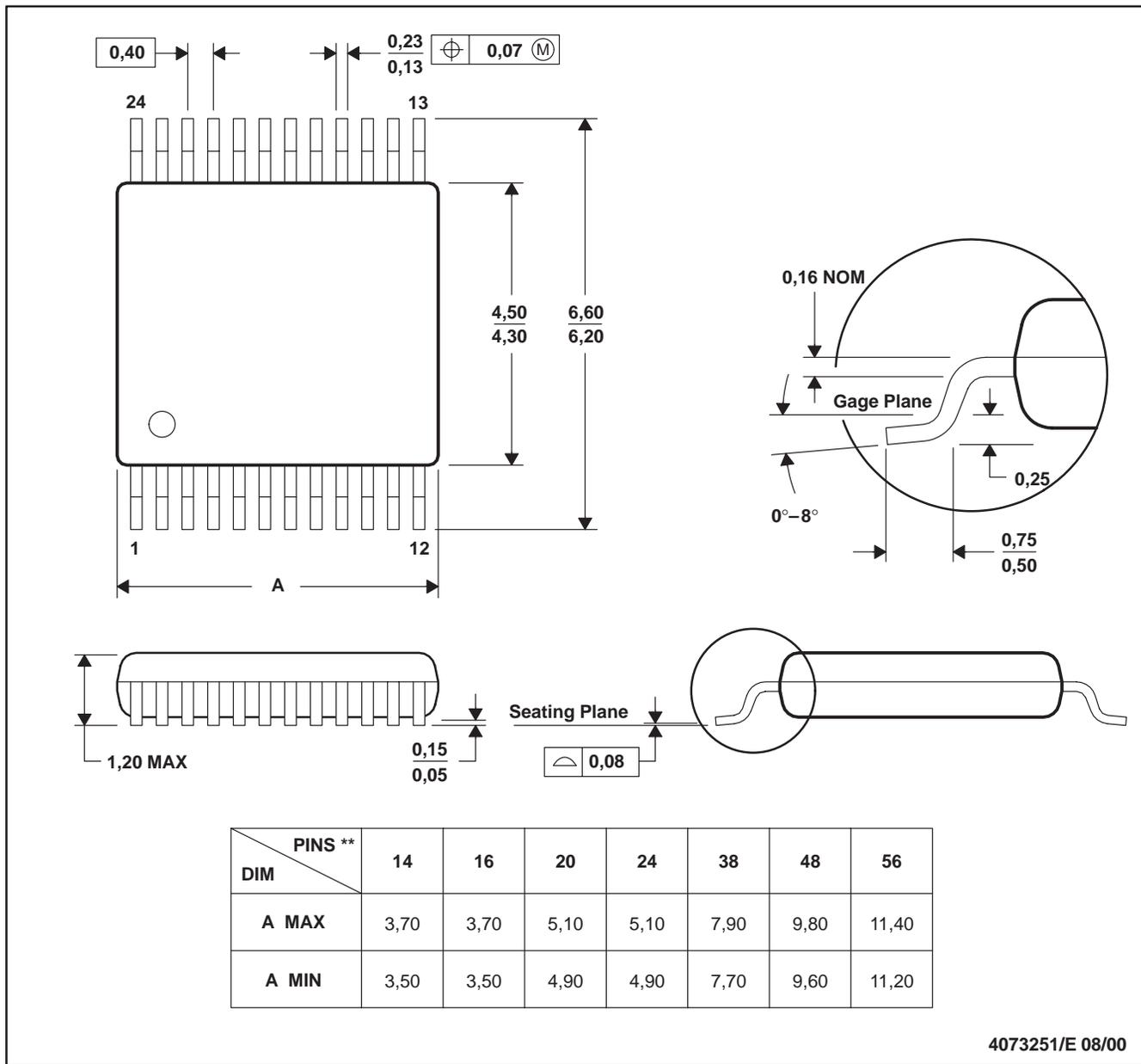
PINS ** DIM	14	16	20	24	38	48	56
A MAX	3,70	3,70	5,10	5,10	7,90	9,80	11,40
A MIN	3,50	3,50	4,90	4,90	7,70	9,60	11,20

4073251/E 08/00

NOTES: A. All linear dimensions are in millimeters.
           B. This drawing is subject to change without notice.
           C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
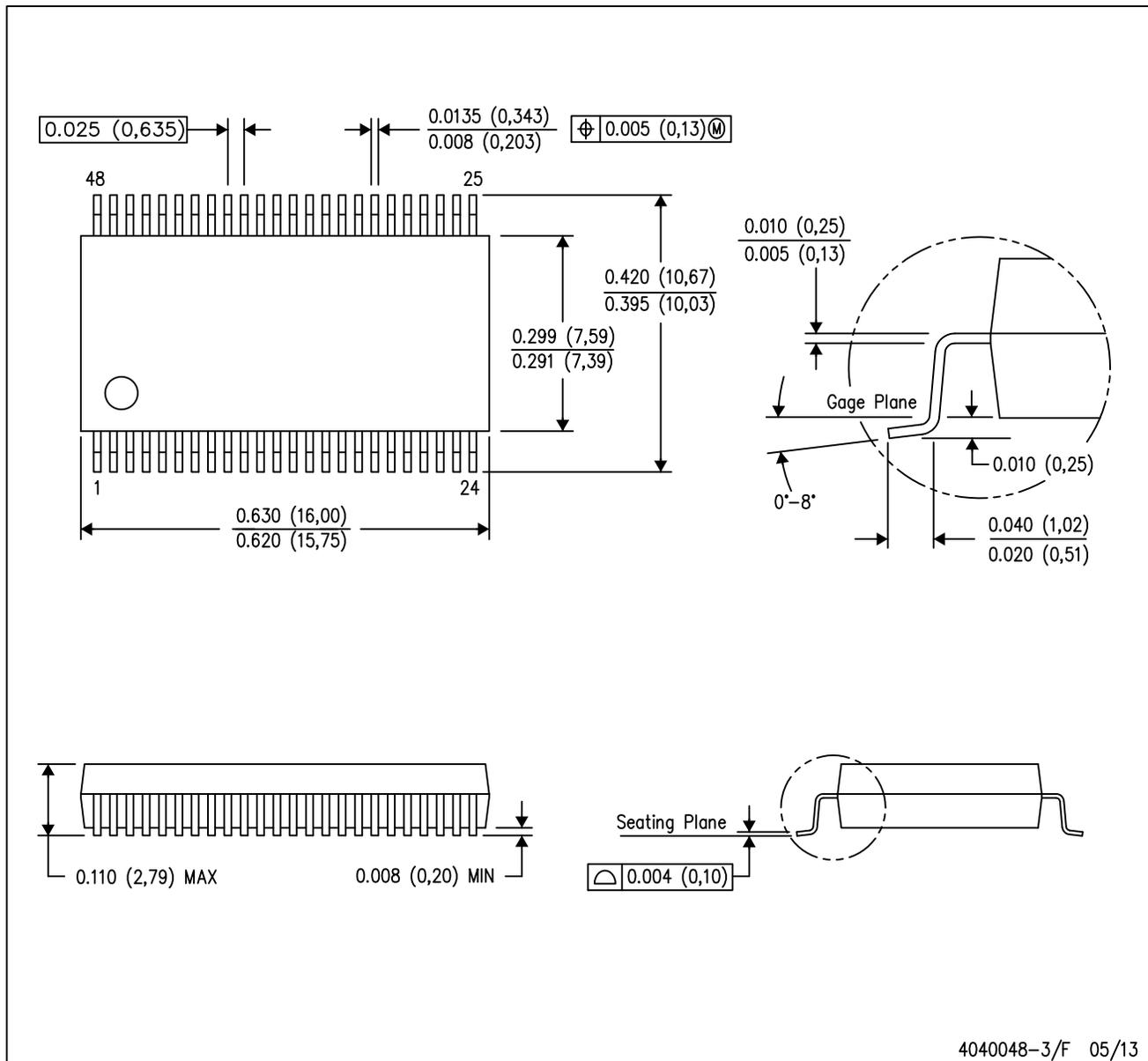   D. Falls within JEDEC: 24/48 Pins – MO-153
                                    14/16/20/56 Pins – MO-194

8.3
7.9 TYP

A

PIN 1 ID
AREA

1

46X 0.5

48

12.6
12.4
NOTE 3

2X
11.5

24

25

B

6.2
6.0

48X 0.27
0.17

⊕ 0.08 Ⓜ C A B

C

SEATING PLANE

⌒ 0.1 C

1.2
1.0

(0.15) TYP

SEE DETAIL A

GAGE PLANE

0.25

0° - 8°

0.75
0.50

0.15
0.05

DETAIL A
TYPICAL
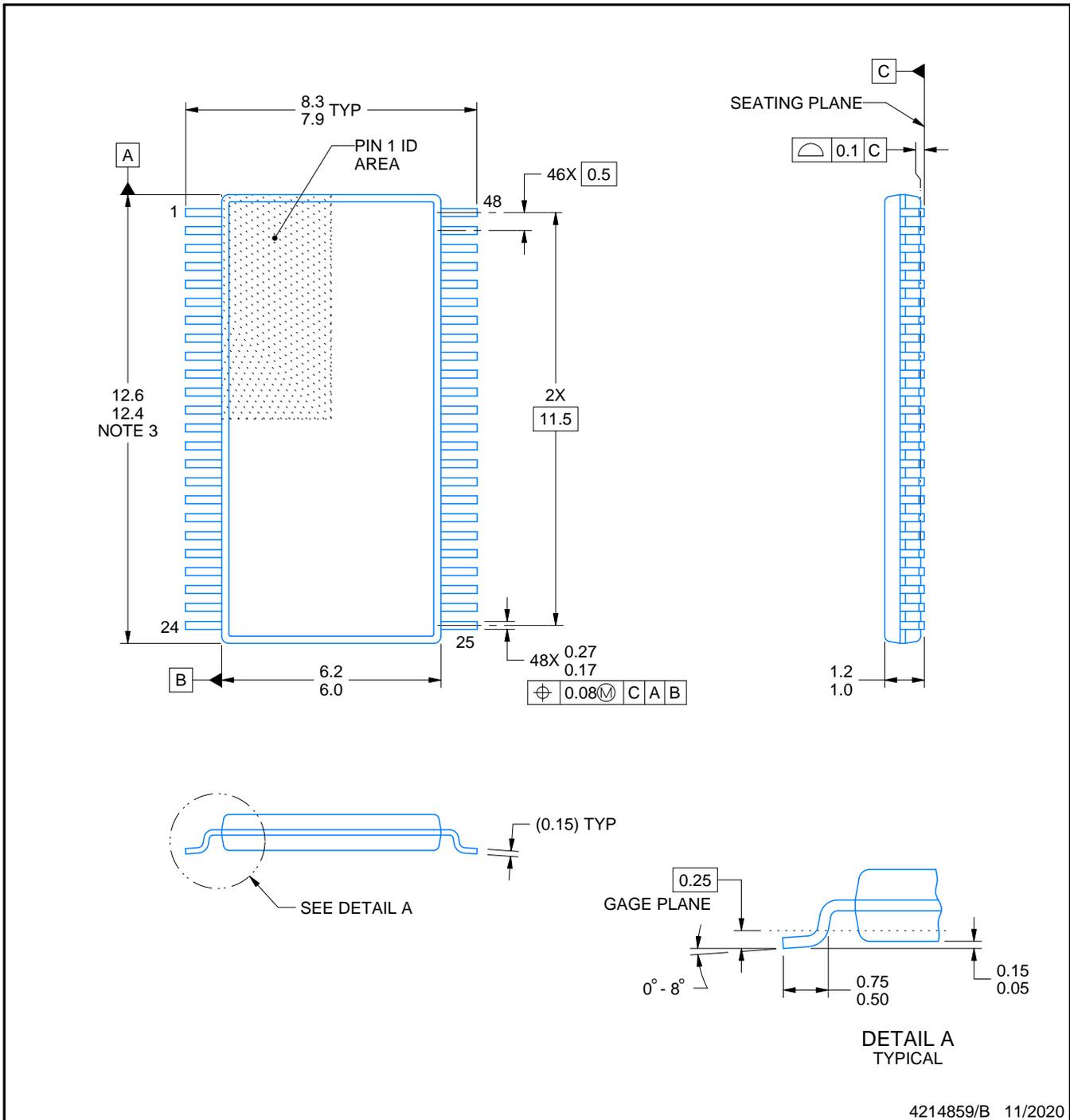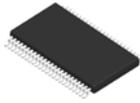
4214859/B   11/2020

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MO-153.

48X (1.5)

SYMM

1

48X (0.3)

48

46X (0.5)

(R0.05)
TYP

SYMM

24

25

(7.5)
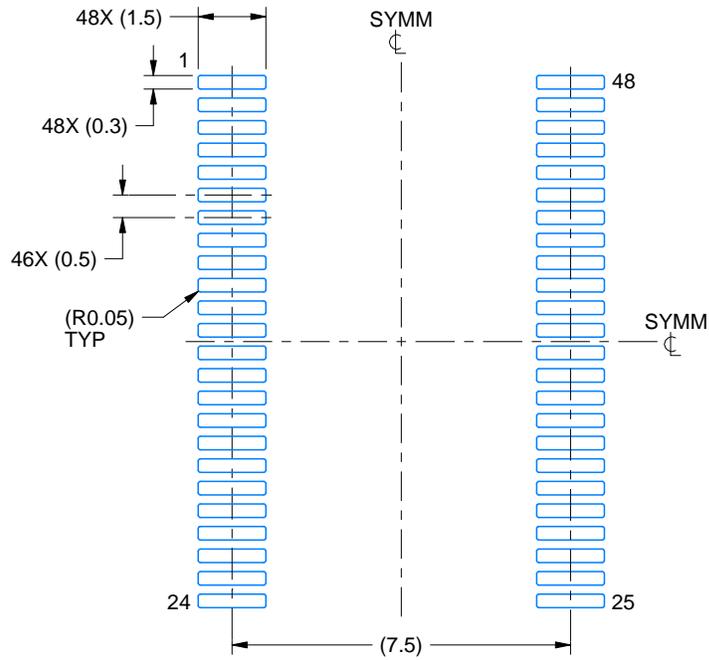
LAND PATTERN EXAMPLE
SCALE:6X

SOLDER MASK
OPENING

METAL

METAL UNDER
SOLDER MASK

SOLDER MASK
OPENING

0.05 MAX
ALL AROUND

0.05 MIN
ALL AROUND

NON SOLDER MASK
DEFINED

SOLDER MASK
DEFINED
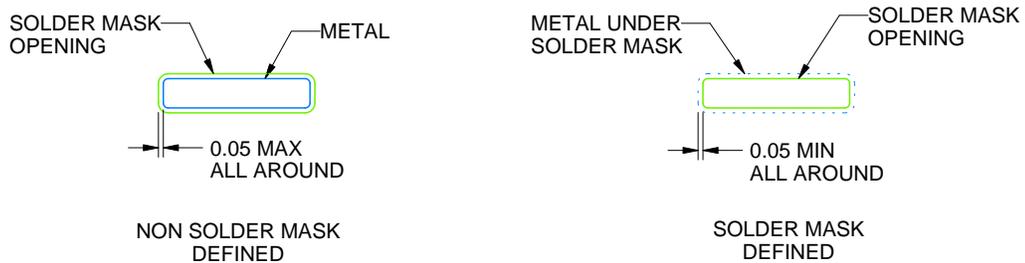
SOLDER MASK DETAILS

4214859/B   11/2020

NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

48X (1.5)

SYMM

1

48

48X (0.3)

46X (0.5)

(R0.05) TYP

SYMM

24

25

(7.5)
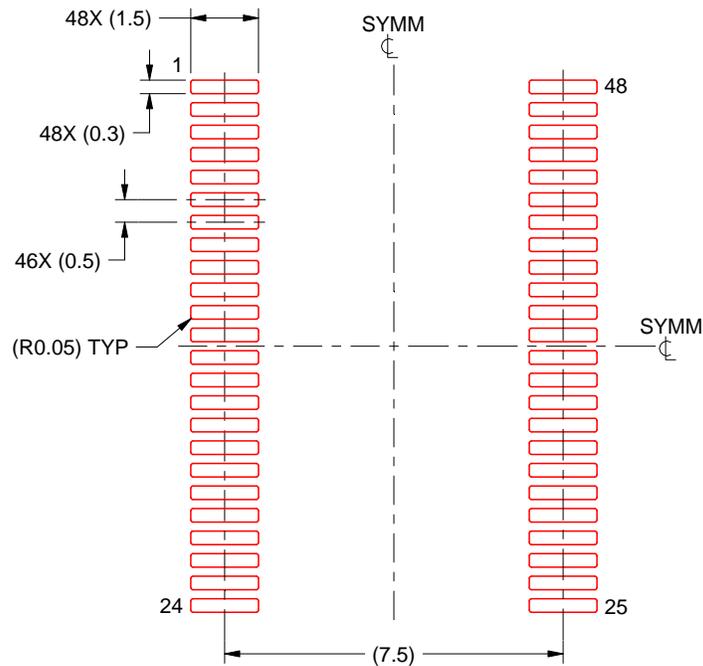
SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:6X

4214859/B   11/2020

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

DGG (R-PDSO-G**)   PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN
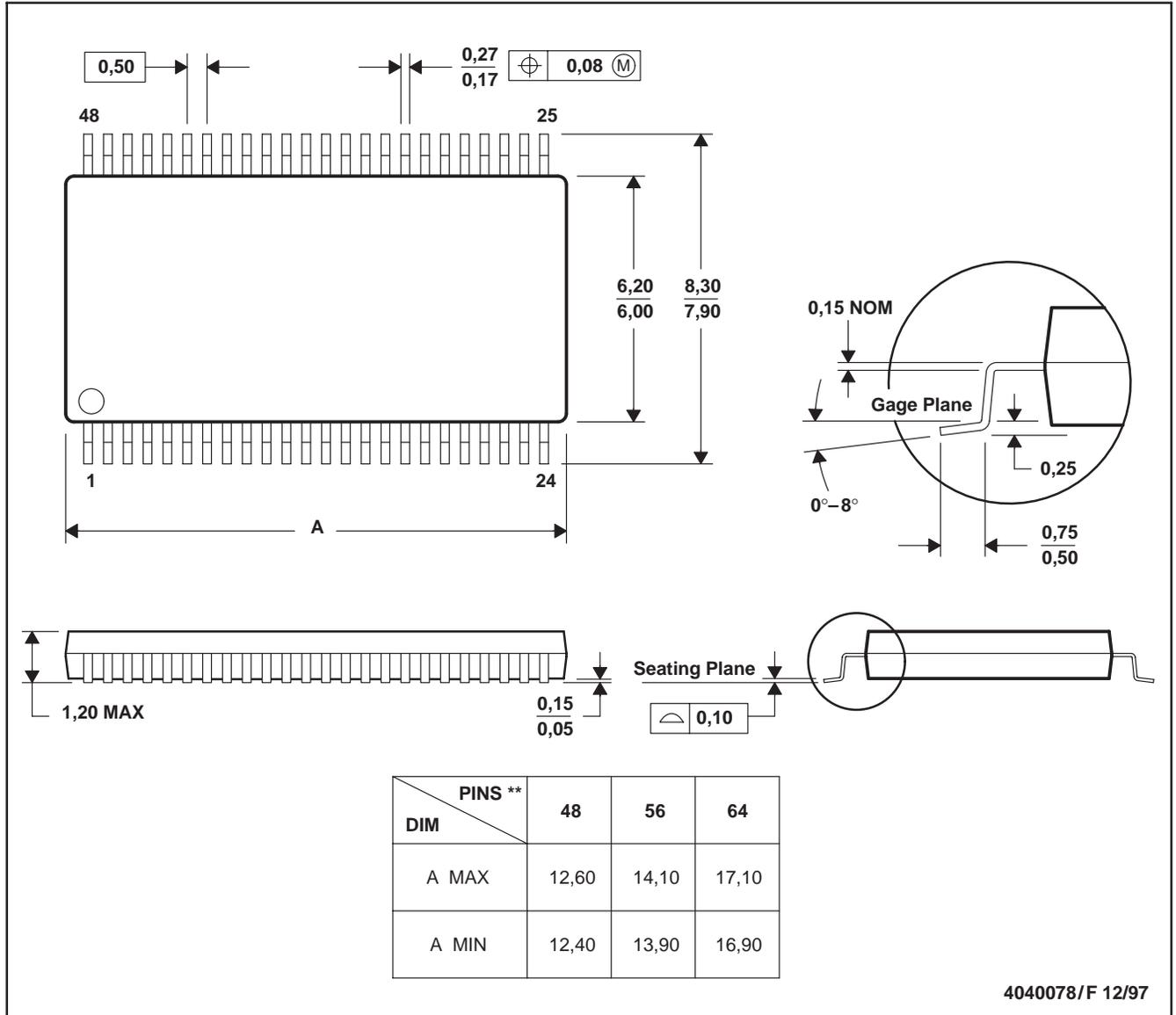
	PINS **	48	56	64
DIM				
A MAX		12,60	14,10	17,10
A MIN		12,40	13,90	16,90

4040078 / F 12/97

NOTES: A. All linear dimensions are in millimeters.
          B. This drawing is subject to change without notice.
          C. Body dimensions do not include mold protrusion not to exceed 0,15.
          D. Falls within JEDEC MO-153

TEXAS INSTRUMENTS

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DL (R−PDSO−G48)   PLASTIC SMALL−OUTLINE PACKAGE

0.025 (0,635)

$\dfrac{0.0135\ (0,343)}{0.008\ (0,203)}$ ⊕ 0.005 (0,13) Ⓜ

48   25

$\dfrac{0.420\ (10,67)}{0.395\ (10,03)}$

$\dfrac{0.299\ (7,59)}{0.291\ (7,39)}$

$\dfrac{0.010\ (0,25)}{0.005\ (0,13)}$

Gage Plane

0.010 (0,25)

0°−8°

1   24

$\dfrac{0.630\ (16,00)}{0.620\ (15,75)}$

$\dfrac{0.040\ (1,02)}{0.020\ (0,51)}$

0.110 (2,79) MAX   0.008 (0,20) MIN

Seating Plane

△ 0.004 (0,10)

4040048−3/F   05/13

NOTES: A.   All linear dimensions are in inches (millimeters).
         B.   This drawing is subject to change without notice.
         C.   Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
         D.   Falls within JEDEC MO−118

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